



◆ **Features**

- 1、 Monolithic Structure for high reliability
- 2、 High self-resonant frequency
- 3、 Excellent solderability and high heat resistance
- 4、 RoHS Compliant.



◆ **Application**

- 1、 RF Circuit of in telecommunication and other Equipments

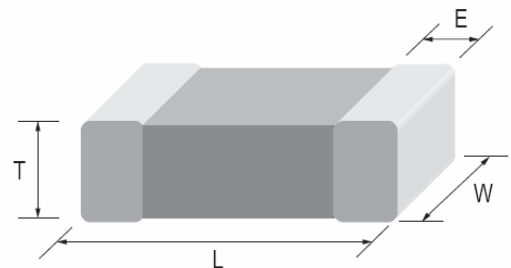
◆ **PRODUCT IDENTIFICATION**

CMCC 2012 C 10N J S P
(1) (2) (3) (4) (5) (6) (7)

- (1) Series Type
- (2) Chip Size (mm) :Length X Width
- (3) Material Code
- (4) Inductance: 1N0=1nH; 10N=10nH
R10=100nH
- (5) Inductance Tolerance: S=±0.3;
J=±5%; K=±10%
- (6) Company Code
- (7) Packaging:P–Embossed paper tape, 7" reel
E- Embossed plastic tape, 7" reel

◆ **Dimensions Unit: mm**

Size(EIA)	2012(0805)
L	2.0 ±0.2
W	1.25±0.2
T	0.85±0.2
E	0.50±0.2



◆ **Specifications**

Part Number	Inductance (nH)	Min. Quality Factor (Q)	L, Q Test Freq. L/Q(MHz)	Typical Q @ Freq. (MHz)			Min. Self-resonant Frequency (MHz)	Max. DC Resistance (Ω)	Max. Rated Current (mA)
				100	800	1000			
CMCC2012 Series									
CMCC2012C1N5SSP	1.5±0.3	10	100	21	61	85	6000	0.10	500
CMCC2012C1N8SSP	1.8±0.3	10	100	20	55	80	6000	0.10	500
CMCC2012C2N2SSP	2.2±0.3	10	100	20	53	75	6000	0.10	500
CMCC2012C2N7SSP	2.7±0.3	12	100	18	56	70	5500	0.10	500
CMCC2012C3N3SSP	3.3±0.3	12	100	18	54	65	5000	0.13	500
CMCC2012C3N9SSP	3.9±0.3	12	100	18	54	60	4500	0.15	500
CMCC2012C4N7SSP	4.7±0.3	12	100	18	55	65	4000	0.20	500
CMCC2012C5N6SSP	5.6±0.3	15	100	18	60	66	3500	0.23	500
CMCC2012C6N8JSP	6.8	15	100	18	63	68	3000	0.25	500
CMCC2012C8N2JSP	8.2	15	100	20	63	70	2500	0.28	500
CMCC2012C10NJSP	10	15	100	21	60	70	2200	0.30	500
CMCC2012C12NJSP	12	15	100	20	60	70	2000	0.35	500
CMCC2012C15NJSP	15	15	100	20	63	65	1800	0.40	500
CMCC2012C18NJSP	18	15	100	22	63	60	1600	0.45	300
CMCC2012C22NJSP	22	15	100	19	60	45	1500	0.50	300
CMCC2012C27NJSP	27	15	100	19	58	38	1400	0.55	300
CMCC2012C33NJSP	33	15	100	19	55	30	1300	0.60	300
CMCC2012C39NJSP	39	15	100	19	47	26	1100	0.65	300
CMCC2012C47NJSP	47	18	100	23	43	20	1000	0.70	300
CMCC2012C56NJSP	56	18	100	22	39	10	900	0.75	300
CMCC2012C68NJSP	68	18	100	22	30	-	850	0.80	300
CMCC2012C82NJSP	82	18	100	22	-	-	800	0.90	300
CMCC2012CR10JSP	100	18	100	22	-	-	700	0.90	300
CMCC2012CR12JSP	120	13	50	19	-	-	600	0.95	300
CMCC2012CR15JSP	150	13	50	19	-	-	550	1.20	300
CMCC2012CR18JSP	180	13	50	19	-	-	500	1.30	300
CMCC2012CR22JSP	220	12	50	20	-	-	400	1.50	300
CMCC2012CR27JSP	270	12	50	20	-	-	350	1.80	300
CMCC2012CR33JSP	330	12	50	18	-	-	300	2.00	300
CMCC2012CR39JSP	390	10	50	17	-	-	250	2.00	300
CMCC2012CR47JSP	470	10	50	17	-	-	200	2.00	300

◆ General Technical Data

Operating Temperature Range	-55°C ~ +125°C
Storage Condition	Less than 40°C and 70% RH
Soldering Method	Reflow or Wave Soldering

◆ Composition / Information on Ingredients

Product Structure: See Fig.1, Fig. 2 and Fig. 3



Fig.1 Shape

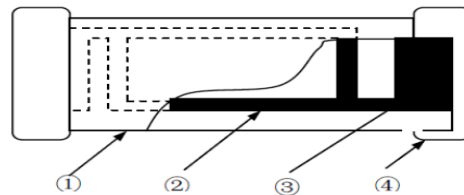


Fig.2 Body Structure

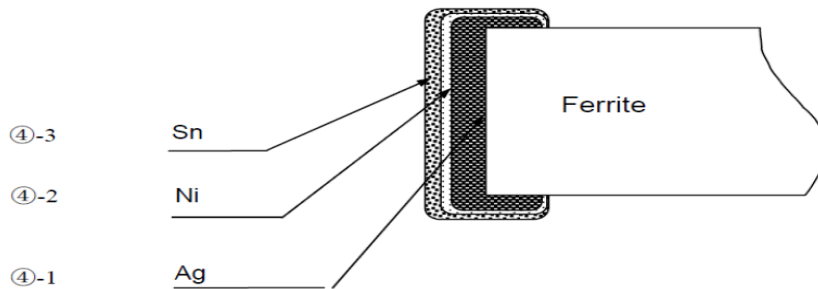


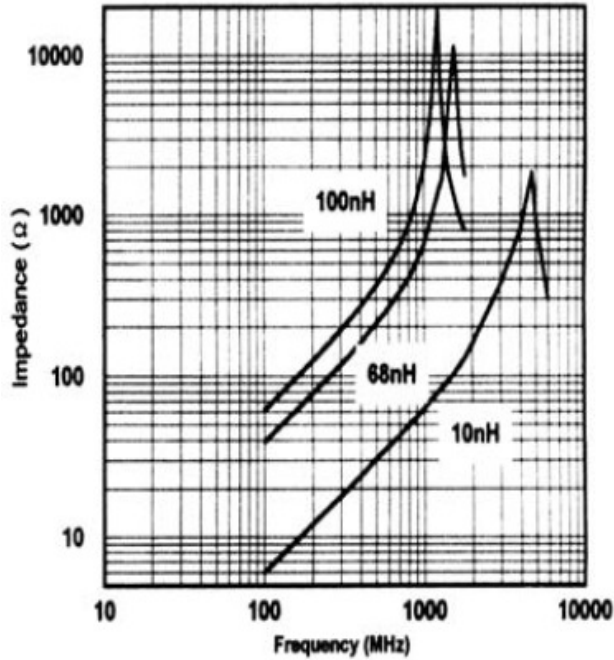
Fig. 3 Structure of Electro-plating

Composition/Information on the Components		
Code	Material	Main Components
①	Ceramic	Boron Silicate, Al ₂ O ₃ , Secret
②	Inner Coil	Silver (Ag)
③	Pull-out Electrode	Silver (Ag)
④-1	Terminal Electrode	Silver (Ag)
④-2	Electrode-plating: Nickel plating	Nickel (Ni)
④-3	Electrode-plating: Sn plating	Tin (Sn)
Compositions Wt Rate (Wt%) of Material		
Material	Wt Rate (Wt%)	CAS No.
Boron Silicate	51~65	65997-18-4
Al ₂ O ₃	14~17	1344-28-1
Secret	0~5	-
Ag	9~29	7440-22-4
Nickel	1.8~2.3	7440-02-0
Tin	3.6~4.7	7440-31-5

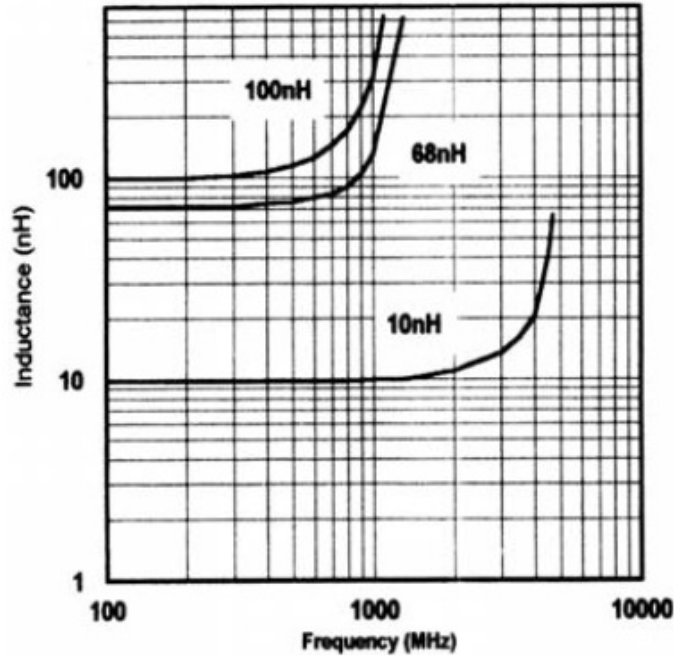
◆ TYPICAL ELECTRICAL CHARACTERISTICS

CMCC2012 Series

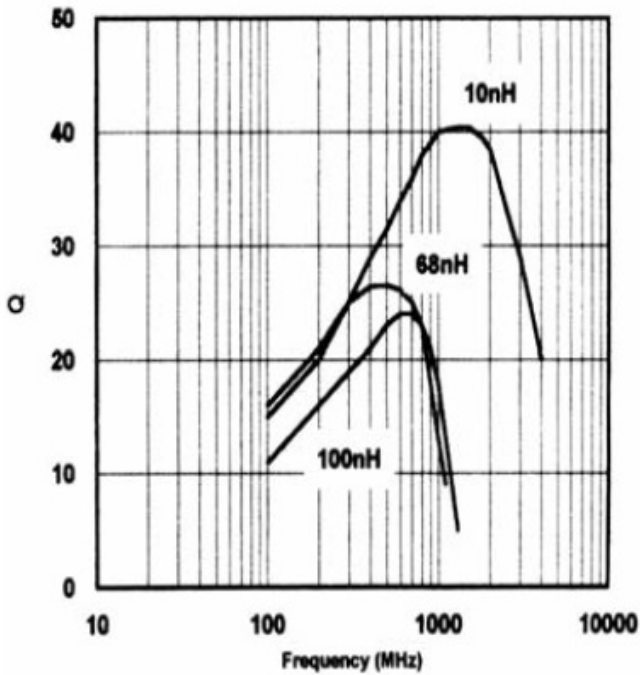
Inductance vs. Frequency Characteristics



Impedance vs. Frequency Characteristics

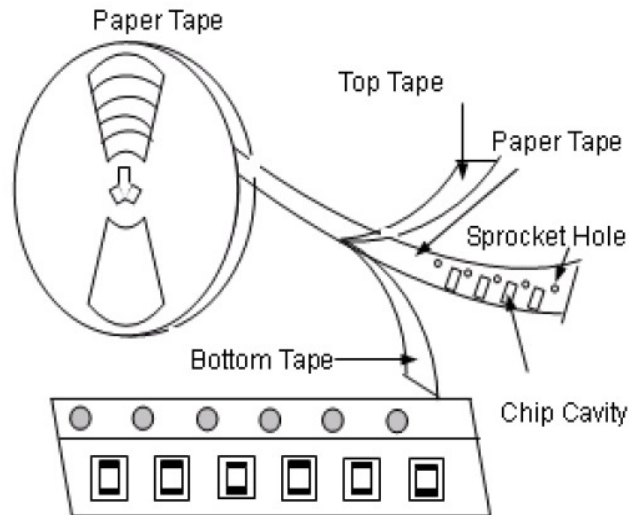


Q vs. Frequency Characteristics



◆ Packaging

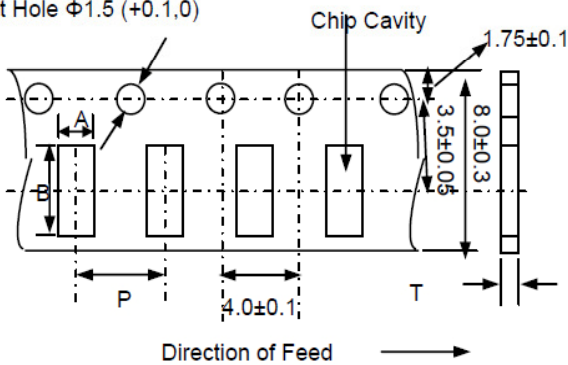
(1) Taping Drawings (Unit: mm)



Remark: The sprocket holes are to the right as the tape is pulled toward the user.

(2) Taping Dimensions (Unit: mm)

Sprocket Hole $\Phi 1.5 (+0.1, 0)$



Paper Tape

Type	A	B	P	T max	Quantity
2012(0805)	1.5±0.2	2.3±0.2	4.0±0.1	1.1	4K

(3) Reel Dimensions (Unit: mm)

